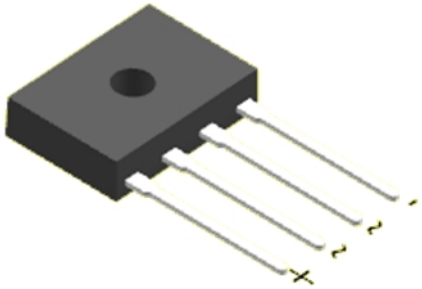
GBP



Features

- ROHS compliant
- Glass passivated chip
- High forward surge capability
- Meet MSL level 1, per J-STD-020 LF maximum peak of 250 °C
- Solder dip 260 °C / 40S
- Component in accordance to ROHS 2002/95/EC and WEEE 2002/96/WC
- UL recognition, file number E342874

Primary characteristics

$I_{F(AV)}$	4A
V_{RRM}	600V to 1000V
I_{FSM}	120A
I_{RM}	5uA
V_{FM} at I_F=2A	1V
T_J max.	150 °C

Applications

Ideal for ac-to-dc bridge full wave rectification suck as SMPS, home applianes, office equipment, indusrial automation applicatios

Mechanical data

- Case: GBP
- Epoxy meets UL 94 V-0 flammability rating
- Terminals: Tin plated leads.
- Polarity: As marked.
- Mounting Torque:10cm-kg(8.8 inches-lbs)max.
- Recommended Torque:5.7 cm-kg(5 inches-lbs)

Maximum rating (Ta=25°C unless otherwise noted)

Parameter		Sym	GBP			Unit
			406	408	410	
Max. repetitive peak reverse voltage		V_{RRM}	600	800	1000	V
Max. RMS reverse voltage		V_{RMS}	420	560	700	V
Max. DC blocking voltage		V_{DC}	600	800	1000	V
Max. average forward current		$I_{F(AV)}$	4			A
Non-repetitive peak forward surge current 8.3ms single half-sine-wave		I_{FSM}	120			A
Rating for fusing,1ms≦ t≦8.3ms		I^2t	76			A^2S
Max. instantaneous forward voltage drop per diode		V_{FM}	1 (2A)			V
Max. instantaneous reverse current at rated DC blocking voltage	Ta=25 °C	I_{RM}	5			μA
	Ta=125 °C		500			μA
Operating junction temperature		T_J	-55 ~ +150			°C
Storage temperature		T_{STG}	-55 ~ +150			°C
Thermal resistance junction to cover (Note2)		$R_{\Theta J-C}$	7.5			°C/W
Typical junction capacitance (Note1)		CJ	40			pF

Notes

(1) Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts

(2) Device mounted on 50mm x 50mm x 2.0mm Cu Plate Heatsink

Ordering information (Example)				
PREFERRED	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
GBP406				

Typical characteristics

FIG.1-FORWARD CURRENT DERATING CURVE

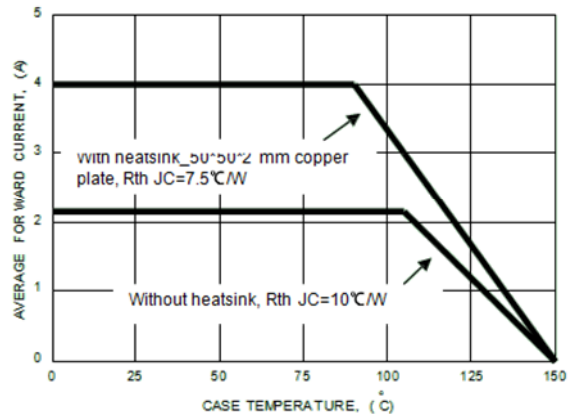


FIG.3-TYPICAL FORWORD CHARACTERISTICS

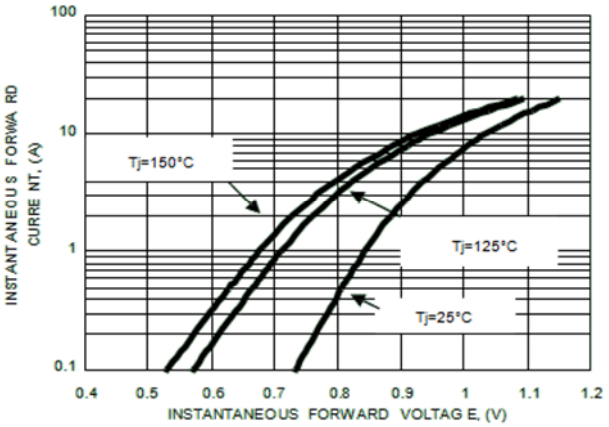


FIG.2-MAXIMUM NON-REPETITIVE SURGE CURRENT

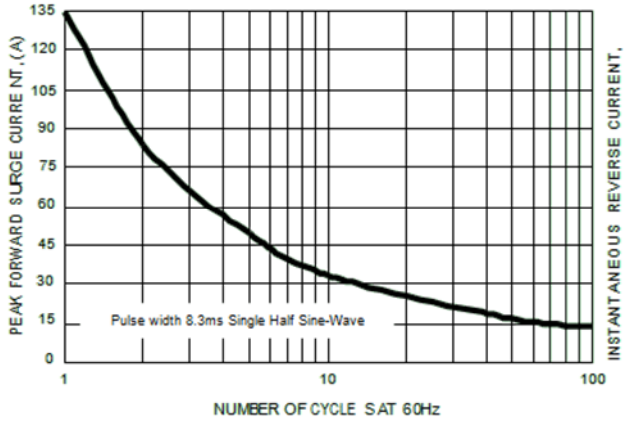
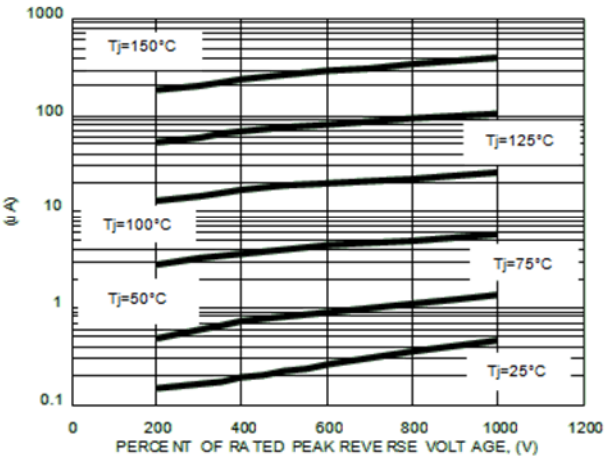
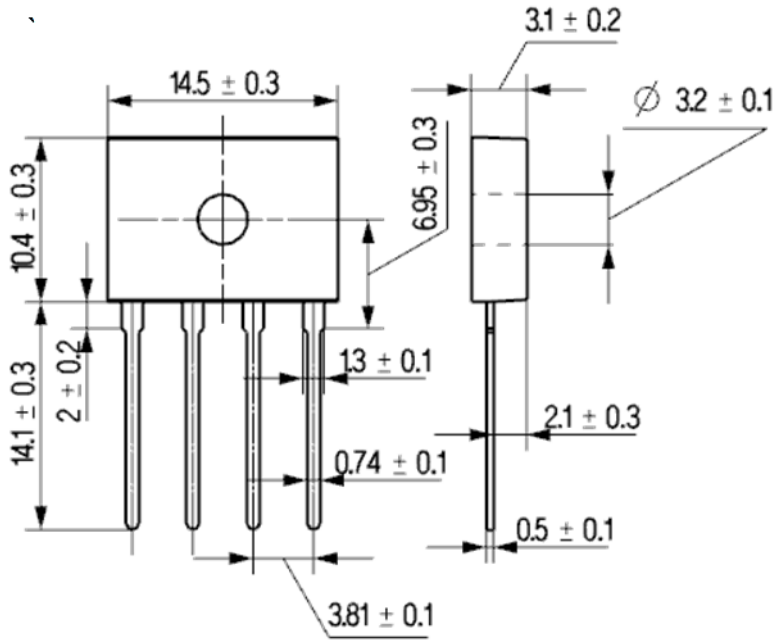


FIG.4-TYPICAL REVERSE CHARACTERISTICS



Package outline dimensions



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